

## -20V P-Channel Enhancement Mode MOSFET

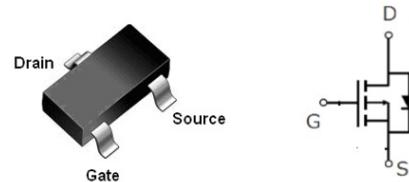
### Features

- Low  $R_{DS(on)}$  @  $V_{GS}=-4.5V$
- -3.3V Logic Level Control
- P Channel SOT23 Package
- Pb-Free, RoHS Compliant

$V_{(BR)DSS}$	$R_{DS(ON)}$ Typ	$I_D$ Max
-20V	115mΩ @ 4.5V	-2.3A
	140mΩ @ 3.3V	

### Applications

- High-side Load Switch
- Switching Circuits
- High Speed line Driver



### Order Information

SOT23

Product	Package	Marking	Packing
AM20DP023M	SOT23	A1SHB	3000PCS/Reel

### Absolute Maximum Ratings

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating	Unit
<b>Common Ratings (TA=25°C Unless Otherwise Noted)</b>			
$V_{GS}$	Gate-Source Voltage	±10	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-20	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C

### Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested <sup>①</sup>	$T_A = 25^\circ C$	-9	A
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-2.3	A
		$T_A = 70^\circ C$	-2.0	
$P_D$	Maximum Power Dissipation	$T_A = 25^\circ C$	1	W
		$T_A = 70^\circ C$	0.8	
$R_{JJA}$	Thermal Resistance Junction-Ambient		125	°C/W

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-20	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current( $T_A=25^\circ\text{C}$ )	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_A=125^\circ\text{C}$ )	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	-100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$ , $V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=-250\mu\text{A}$	-0.4	-0.6	-1.0	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>②</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-2\text{A}$	--	115	138	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>②</sup>	$V_{\text{GS}}=-3.3\text{V}$ , $I_D=-1\text{A}$	--	140	170	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>②</sup>	$V_{\text{GS}}=-2.5\text{V}$ , $I_D=-1\text{A}$	--	170	210	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	--	177	--	pF
$C_{\text{oss}}$	Output Capacitance		--	30	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	25	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-10\text{V}$ $I_D=-2\text{A}$ , $V_{\text{GS}}=-4.5\text{V}$	--	5.3	--	nC
$Q_{\text{gs}}$	Gate Source Charge		--	0.7	--	nC
$Q_{\text{gd}}$	Gate Drain Charge		--	1.4	--	nC
<b>Switching Characteristics</b>						
$t_{\text{d(on)}}$	Turn on Delay Time	$V_{\text{DD}}=-10\text{V}$ , $I_D=-2\text{A}$ , $R_G=3.3\Omega$ , $V_{\text{GS}}=-4.5\text{V}$	--	11	--	ns
$t_r$	Turn on Rise Time		--	32	--	ns
$t_{\text{d(off)}}$	Turn Off Delay Time		-	25	--	ns
$t_f$	Turn Off Fall Time		--	38	--	ns
<b>Source Drain Diode Characteristics</b>						
$I_{\text{SD}}$	Source drain current(Body Diode)	$T_A=25^\circ\text{C}$	--	--	-1.2	A
$V_{\text{SD}}$	Forward on voltage <sup>②</sup>	$T_j=25^\circ\text{C}$ , $I_{\text{SD}}=-1\text{A}$ , $V_{\text{GS}}=0\text{V}$	--	-0.83	-1.2	V

Notes:

① Pulse width limited by maximum allowable junction temperature

② Pulse test ; Pulse width $\leq 300\mu\text{s}$ , duty cycle $\leq 2\%$ .

## Typical Characteristics

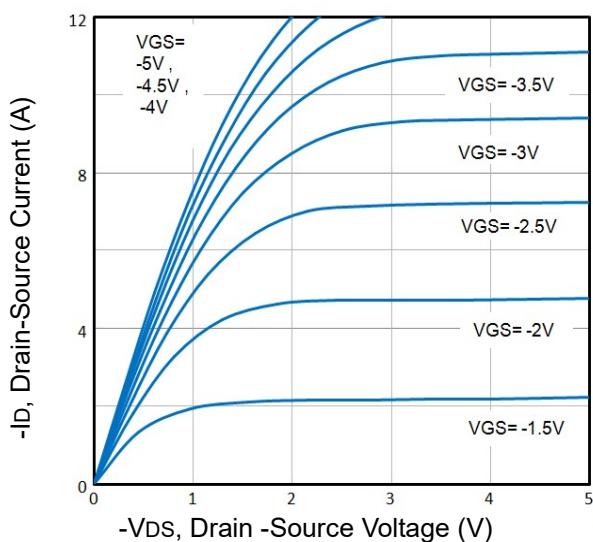


Fig1. Typical Output Characteristics

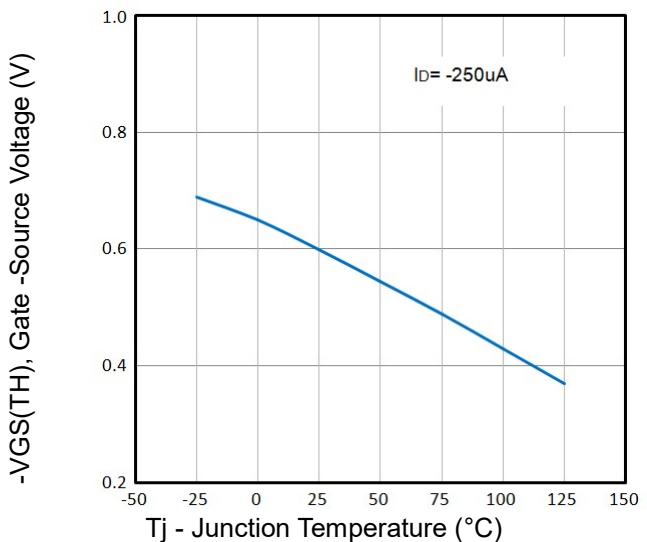


Fig2. Normalized Threshold Voltage Vs. Temperature

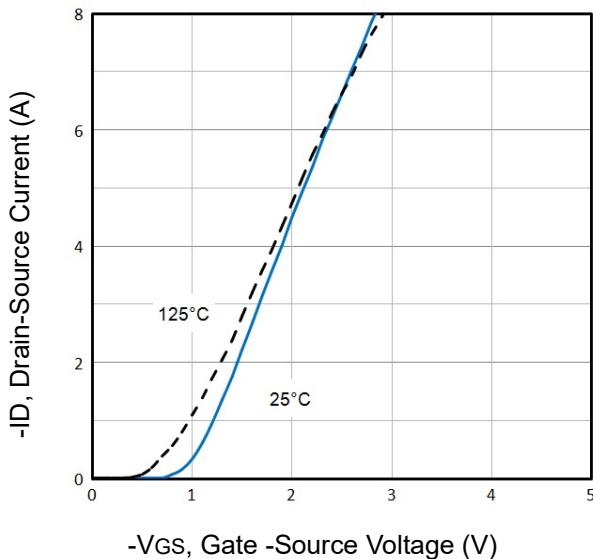


Fig3. Typical Transfer Characteristics

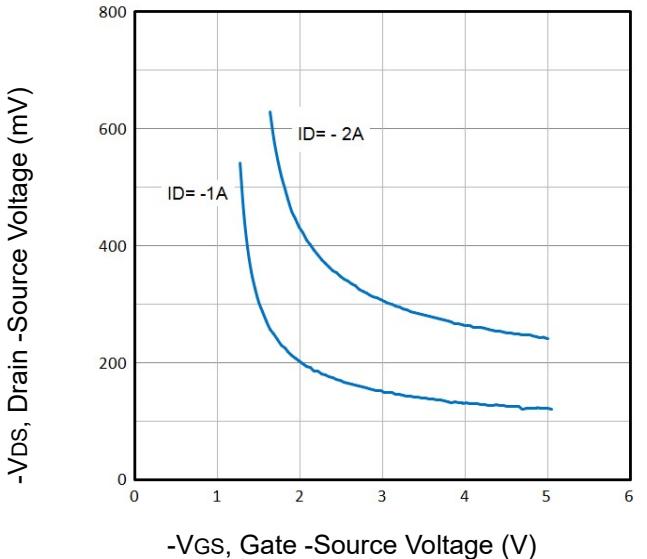


Fig4. Drain -Source Voltage vs Gate -Source Voltage

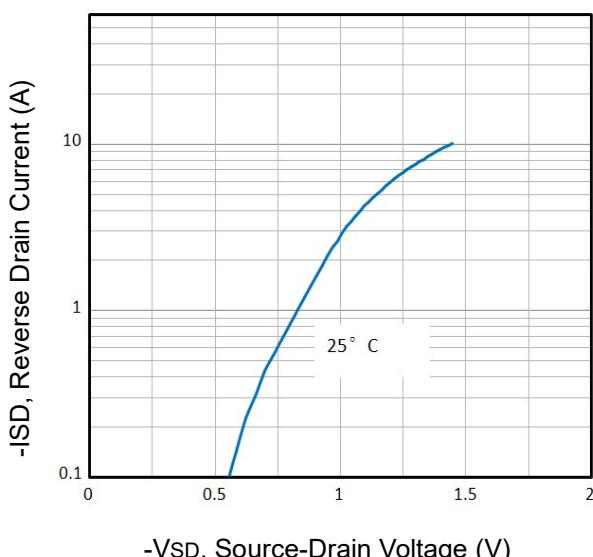


Fig5. Typical Source-Drain Diode Forward Voltage

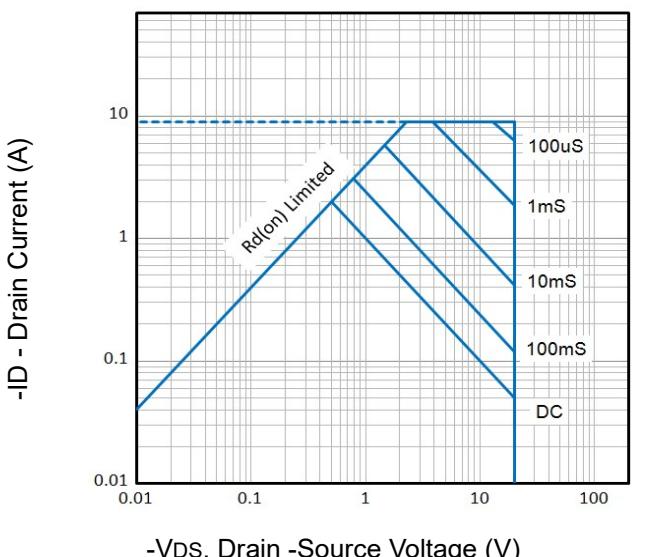


Fig6. Maximum Safe Operating Area

## Typical Characteristics

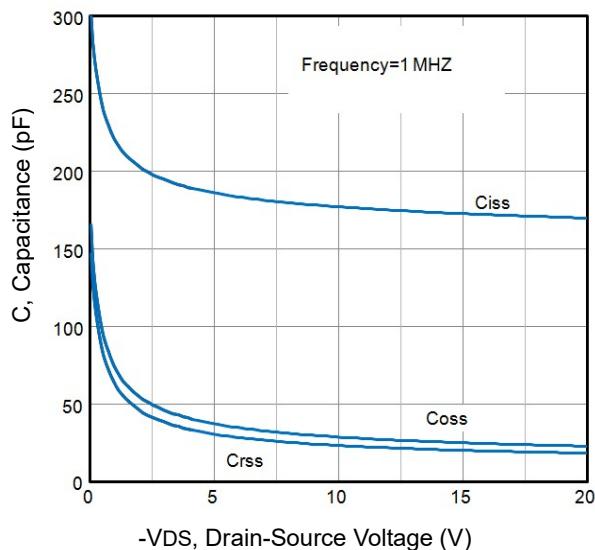


Fig7. Typical Capacitance Vs. Drain-Source Voltage

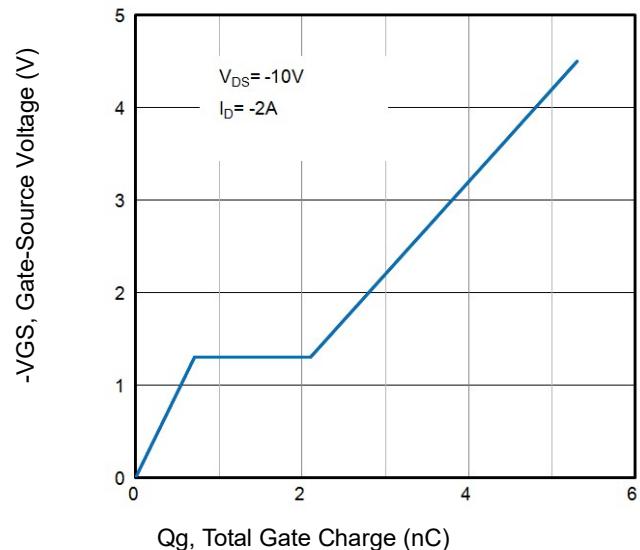


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

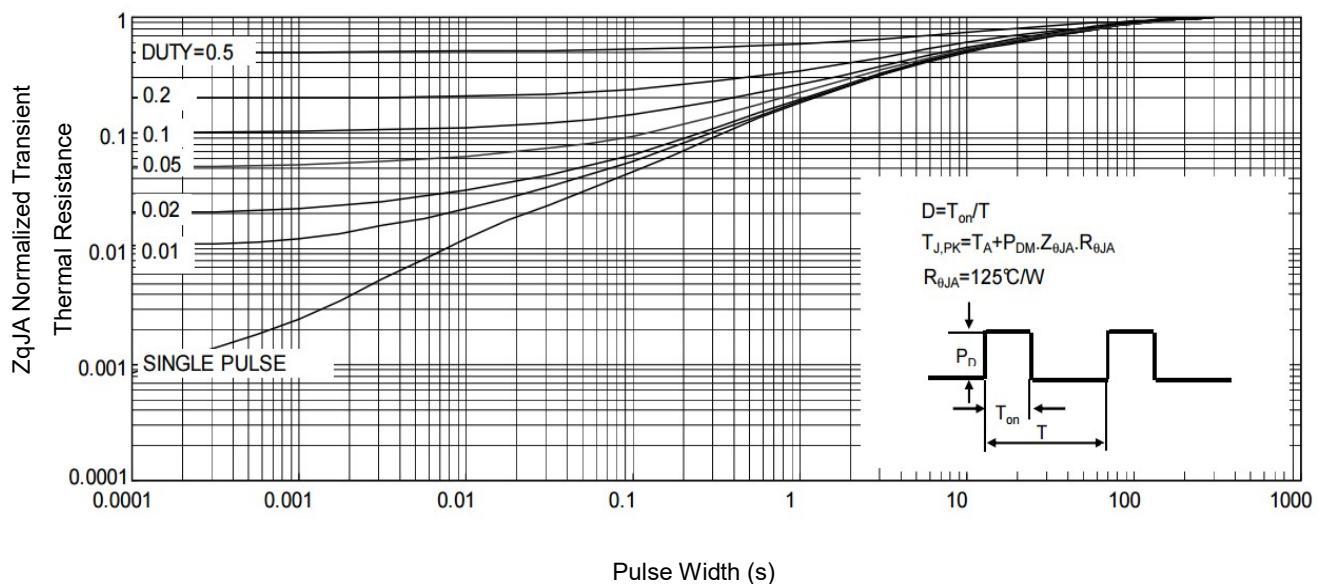


Fig9. Normalized Maximum Transient Thermal Impedance

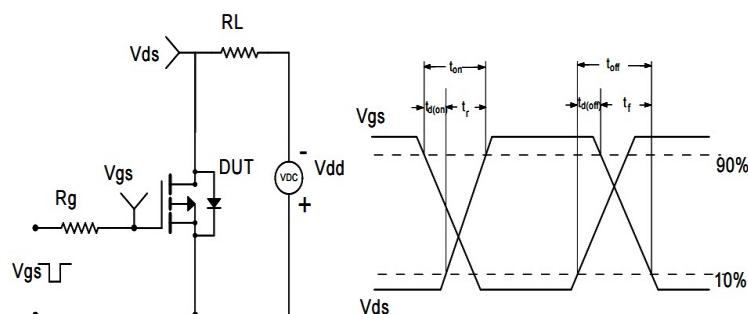
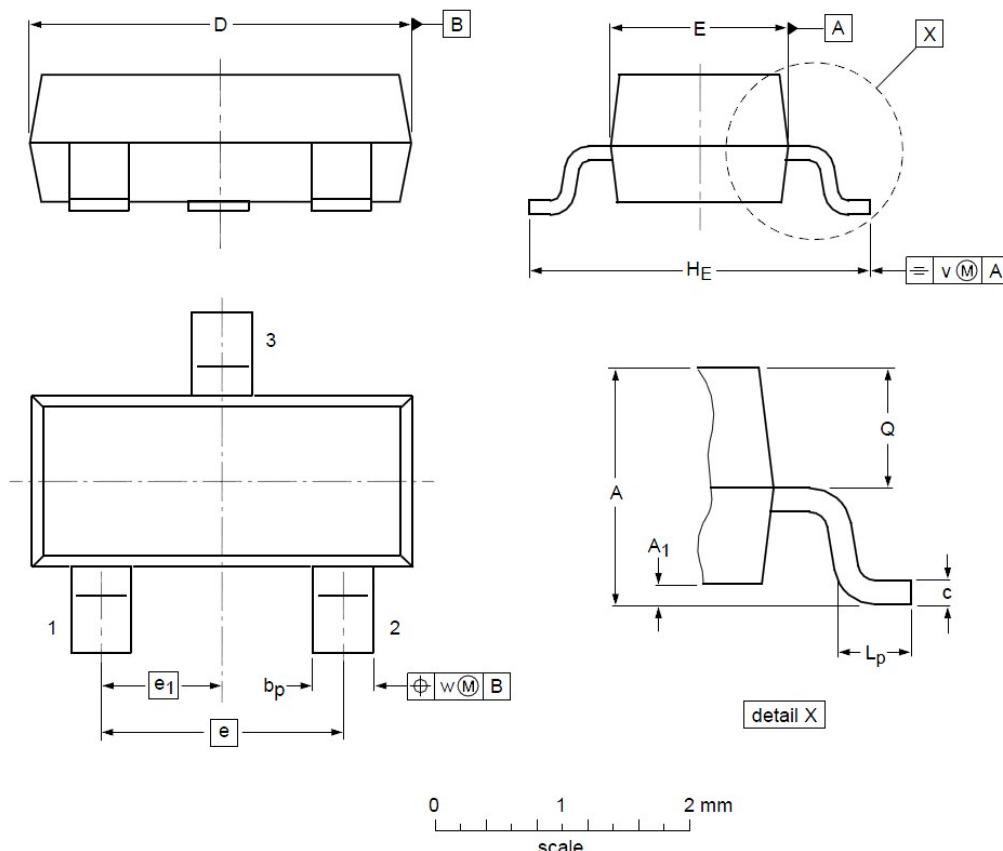


Fig10. Switching Time Test Circuit and waveforms

## SOT23 Mechanical Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A <sub>1</sub>	0.01	0.05	0.10
b <sub>p</sub>	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e <sub>1</sub>	--	0.95	--
H <sub>E</sub>	2.25	2.40	2.55	L <sub>p</sub>	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

## SOT-23 Suggested Pad Layout

